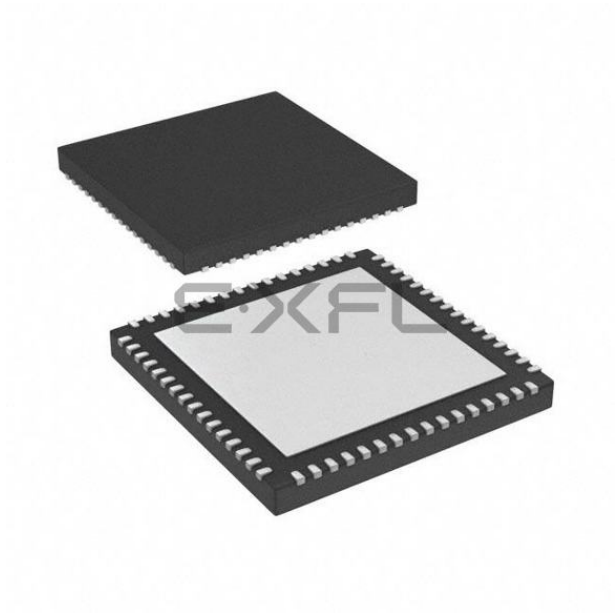
Microchip Technology - PIC32MX350F128HT-I/RG Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f128ht-i-rg

TABLE 4: PIN NAMES FOR 100-PIN DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)(1,2,3)

PIC32MX330F064L
PIC32MX350F128L
PIC32MX350F256L
PIC32MX370F512L

Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMCS1/RD11	86	VDD
72	RPD0/RD0	87	RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	TRCLK/RA6
77	AN25/RPD2/RD2	92	TRD3/CTED8/RA7
78	AN26/RPD3/RD3	93	PMD0/RE0
79	RPD12/PMD12/RD12	94	PMD1/RE1
80	PMD13/RD13	95	TRD2/RG14
81	RPD4/PMWR/RD4	96	TRD1/RG12
82	RPD5/PMRD/RD5	97	TRD0/RG13
83	PMD14/RD6	98	AN20/PMD2/RE2
84	PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: RPF6 (pin 55) and RPF7 (pin 54) are only remappable for input functions.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
CTED4	22	33	B19	I	ST	CTMU External Edge Input 4
CTED5	29	43	B24	I	ST	CTMU External Edge Input 5
CTED6	30	44	A29	I	ST	CTMU External Edge Input 6
CTED7	—	9	B5	I	ST	CTMU External Edge Input 7
CTED8	—	92	A62	I	ST	CTMU External Edge Input 8
CTED9	—	60	A40	I	ST	CTMU External Edge Input 9
CTED10	21	32	A23	I	ST	CTMU External Edge Input 10
CTED11	23	34	A24	I	ST	CTMU External Edge Input 11
CTED12	15	24	A15	I	ST	CTMU External Edge Input 12
CTED13	14	23	B13	I	ST	CTMU External Edge Input 13
$\overline{MCLR}$	7	13	B7	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	19	30	A22	P	P	Positive supply for analog modules. This pin must be connected at all times.
AVSS	20	31	B18	P	P	Ground reference for analog modules
VDD	10, 26, 38, 57	2, 16, 37, 46, 62, 86	B1, A10, A14, B21, A30, A41, A48, A59, B53	P	—	Positive supply for peripheral logic and I/O pins
VCAP	56	85	B48	P	—	Capacitor for Internal Voltage Regulator
VSS	9, 25, 41	15, 36, 45, 65, 75	A3, B8, B12, A25, B25, A43, B41, A63	P	—	Ground reference for logic and I/O pins
VREF+	16	29	B17	I	Analog	Analog Voltage Reference (High) Input
VREF-	15	28	A21	I	Analog	Analog Voltage Reference (Low) Input

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input
TTL = TTL input buffer

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

NOTES:

TABLE 7-2: INTERRUPT REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
10F0	IPC6	31:16	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000
		15:0	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
1100	IPC7	31:16	—	—	—	U1IP<2:0>			U1IS<1:0>		—	—	—	SPI1IP<2:0>			SPI1IS<1:0>		0000
		15:0	—	—	—	USBIP<2:0>(2)			USBIS<1:0>(2)		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
1110	IPC8	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
		15:0	—	—	—	CNIP<2:0>			CNIS<1:0>		—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		0000
1120	IPC9	31:16	—	—	—	U4IP<2:0>			U4IS<1:0>		—	—	—	U3IP<2:0>			U3IS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1130	IPC10	31:16	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>		—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
		15:0	—	—	—	CTMUIP<2:0>			CTMUIS<1:0>		—	—	—	U5IP<2:0>			U5IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>		—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This bit is only available on 100-pin devices.

2: This bit is only implemented on devices with a USB module.

REGISTER 10-18: DCHxDAT: DMA CHANNEL 'x' PATTERN DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHPDAT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **CHPDAT<7:0>:** Channel Data Register bits

Pattern Terminate mode:
Data to be matched must be stored in this register to allow terminate on match.

All other modes:
Unused.

REGISTER 11-1: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	U-0	R/WC-0, HS
	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **IDIF:** ID State Change Indicator bit
- 1 = Change in ID state is detected
- 0 = No change in ID state is detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit
- 1 = 1 millisecond timer has expired
- 0 = 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit
- 1 = USB line state has been stable for 1millisecond, but different from last time
- 0 = USB line state has not been stable for 1 millisecond

bit 4 **ACTVIF:** Bus Activity Indicator bit
- 1 = Activity on the D+, D-, ID or VBUS pins has caused the device to wake-up
- 0 = Activity has not been detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit
- 1 = VBUS voltage has dropped below the session end level
- 0 = VBUS voltage has not dropped below the session end level

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit
- 1 = A change on the session end input was detected
- 0 = No change on the session end input was detected

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit
- 1 = Change on the session valid input is detected
- 0 = No change on the session valid input is detected

REGISTER 11-3: U1OTGSTAT: USB OTG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	U-0	R-0	U-0	R-0	R-0	U-0	R-0
	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **ID:** ID Pin State Indicator bit
- 1 = No cable is attached or a Type-B cable has been plugged into the USB receptacle
- 0 = A Type-A cable has been plugged into the USB receptacle

bit 6 **Unimplemented:** Read as '0'

bit 5 **LSTATE:** Line State Stable Indicator bit
- 1 = USB line state (U1CON<SE0> and U1CON<JSTATE>) has been stable for the previous 1 ms
- 0 = USB line state (U1CON<SE0> and U1CON<JSTATE>) has not been stable for the previous 1 ms

bit 4 **Unimplemented:** Read as '0'

bit 3 **SESVD:** Session Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A or B device
- 0 = VBUS voltage is below Session Valid on the A or B device

bit 2 **SESEND:** B-Device Session End Indicator bit
- 1 = VBUS voltage is below Session Valid on the B device
- 0 = VBUS voltage is above Session Valid on the B device

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVD:** A-Device VBUS Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A device
- 0 = VBUS voltage is below Session Valid on the A device

REGISTER 11-10: U1STAT: USB STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R-x	R-x	R-x	R-x	U-0	U-0
	ENDPT<3:0>				DIR	PPBI	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **ENDPT<3:0>:** Encoded Number of Last Endpoint Activity bits
(Represents the number of the BDT, updated by the last USB transfer.)

1111 = Endpoint 15
1110 = Endpoint 14
•
•
•
0001 = Endpoint 1
0000 = Endpoint 0

bit 3 **DIR:** Last BD Direction Indicator bit

1 = Last transaction was a transmit transfer (TX)
0 = Last transaction was a receive transfer (RX)

bit 2 **PPBI:** Ping-Pong BD Pointer Indicator bit

1 = The last transaction was to the ODD BD bank
0 = The last transaction was to the EVEN BD bank

bit 1-0 **Unimplemented:** Read as '0'

Note: The U1STAT register is a window into a 4-byte FIFO maintained by the USB module. U1STAT value is only valid when the TRNIF bit (U1IR<3>) is active. Clearing the TRNIF bit advances the FIFO. Data in register is invalid when the TRNIF bit = 0.

12.0 I/O PORTS

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS60001120), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

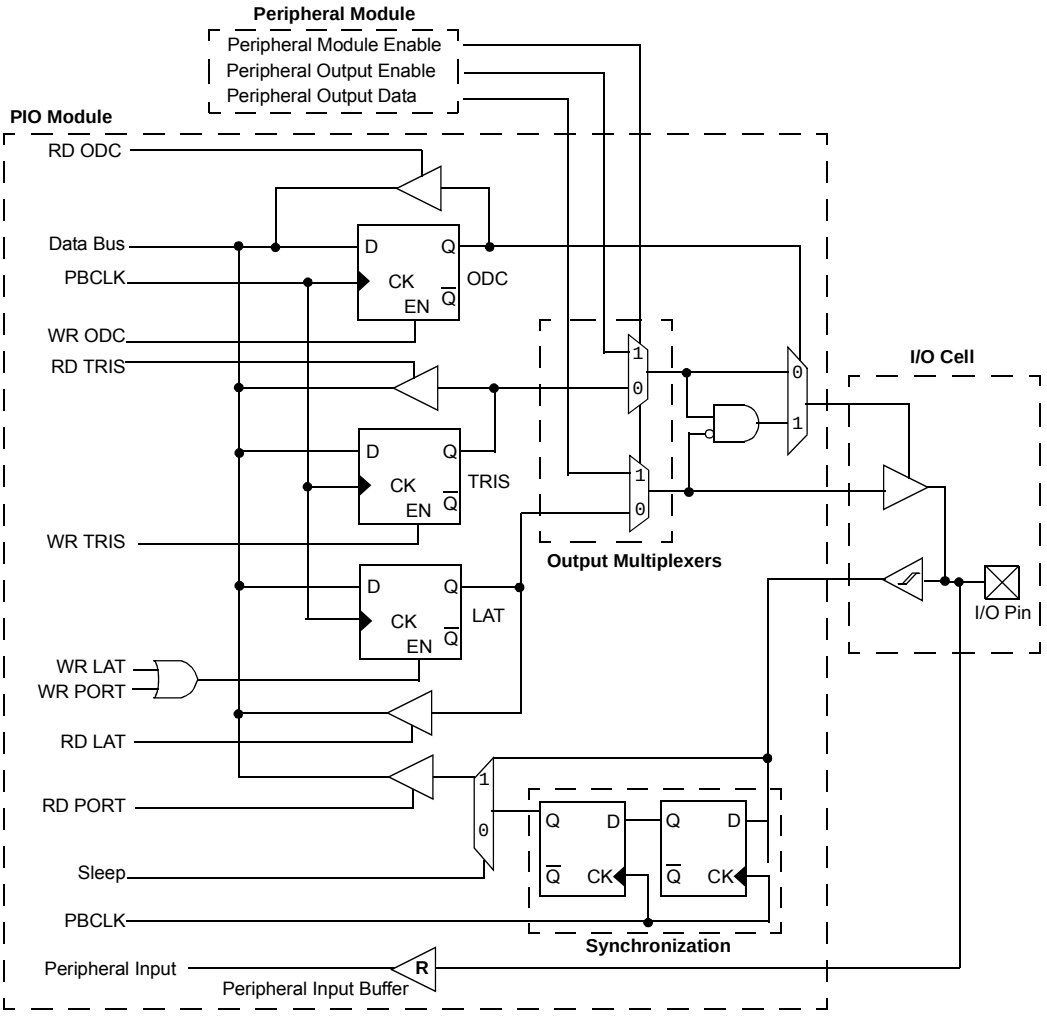
General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate function(s). These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Following are key features of this module:

- Individual output pin open-drain enable/disable
- Individual input pin weak pull-up and pull-down
- Monitor selective inputs and generate interrupt when change in pin state is detected
- Operation during CPU Sleep and Idle modes
- Fast bit manipulation using CLR, SET, and INV registers

Figure 12-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 12-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure for illustration purposes only. The actual structure for any specific port/peripheral combination may be different than it is shown here.

REGISTER 20-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 8 **TRMT:** Transmit Shift Register is Empty bit (read-only)
1 = Transmit shift register is empty and transmit buffer is empty (the last transmission has completed)
0 = Transmit shift register is not empty, a transmission is in progress or queued in the transmit buffer

bit 7-6 **URXISEL<1:0>:** Receive Interrupt Mode Selection bit
11 = Reserved; do not use
10 = Interrupt flag bit is asserted while receive buffer is 3/4 or more full (i.e., has 6 or more data characters)
01 = Interrupt flag bit is asserted while receive buffer is 1/2 or more full (i.e., has 4 or more data characters)
00 = Interrupt flag bit is asserted while receive buffer is not empty (i.e., has at least 1 data character)

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)
1 = Address Detect mode is enabled. If 9-bit mode is not selected, this control bit has no effect
0 = Address Detect mode is disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)
1 = Receiver is Idle
0 = Data is being received

bit 3 **PERR:** Parity Error Status bit (read-only)
1 = Parity error has been detected for the current character
0 = Parity error has not been detected

bit 2 **FERR:** Framing Error Status bit (read-only)
1 = Framing error has been detected for the current character
0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit.
This bit is set in hardware and can only be cleared (= 0) in software. Clearing a previously set OERR bit resets the receiver buffer and RSR to empty state.
1 = Receive buffer has overflowed
0 = Receive buffer has not overflowed

bit 0 **URXDA:** Receive Buffer Data Available bit (read-only)
1 = Receive buffer has data, at least one more character can be read
0 = Receive buffer is empty

REGISTER 22-2: RTCALRM: RTC ALARM CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	ALRMEN(1,2)	CHIME(2)	PIV(2)	ALRMSYNC(3)	AMASK<3:0>(3)			
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ARPT<7:0>(3)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ALRMEN:** Alarm Enable bit(1,2)
- 1 = Alarm is enabled
- 0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit(2)
- 1 = Chime is enabled – ARPT<7:0> is allowed to rollover from 0x00 to 0xFF
- 0 = Chime is disabled – ARPT<7:0> stops once it reaches 0x00

bit 13 **PIV:** Alarm Pulse Initial Value bit(2)

When ALRMEN = 0, PIV is writable and determines the initial value of the Alarm Pulse.
When ALRMEN = 1, PIV is read-only and returns the state of the Alarm Pulse.

bit 12 **ALRMSYNC:** Alarm Sync bit(3)
- 1 = ARPT<7:0> and ALRMEN may change as a result of a half second rollover during a read. The ARPT must be read repeatedly until the same value is read twice. This must be done since multiple bits may be changing, which are then synchronized to the PB clock domain
- 0 = ARPT<7:0> and ALRMEN can be read without concerns of rollover because the prescaler is > 32 RTC clocks away from a half-second rollover

bit 11-8 **AMASK<3:0>:** Alarm Mask Configuration bits(3)
- 0000 = Every half-second
- 0001 = Every second
- 0010 = Every 10 seconds
- 0011 = Every minute
- 0100 = Every 10 minutes
- 0101 = Every hour
- 0110 = Once a day
- 0111 = Once a week
- 1000 = Once a month
- 1001 = Once a year (except when configured for February 29, once every four years)
- 1010 = Reserved; do not use
- 1011 = Reserved; do not use
- 11xx = Reserved; do not use

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN(1)	EDGEN	EDGSEQEN	IDISSEN(2)	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **EDG1MOD:** Edge 1 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 programmed for a positive edge response
0 = Edge 1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = Reserved
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = IC3 Capture Event is selected
1011 = IC2 Capture Event is selected
1010 = IC1 Capture Event is selected
1001 = CTED8 pin is selected
1000 = CTED7 pin is selected
0111 = CTED6 pin is selected
0110 = CTED5 pin is selected
0101 = CTED4 pin is selected
0100 = CTED3 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control edge source
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

28.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. "Configuration"** (DS60001124) and **Section 33. "Programming and Diagnostics"** (DS60001129), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX330/350/370/430/450/470 family of devices include several features intended to maximize application flexibility and reliability and minimize cost through elimination of external components. These are:

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

28.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- DEVCFG0: Device Configuration Word 0
- DEVCFG1: Device Configuration Word 1
- DEVCFG2: Device Configuration Word 2
- DEVCFG3: Device Configuration Word 3
- CFGCON: Configuration Control Register

In addition, the DEVID register (Register 28-6) provides device and revision information.

TABLE 31-14: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303	TRESP	Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Notes 1,2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	μs	Comparator module is configured before setting the comparator ON bit **(Note 2)**
D305	IVREF	Internal Voltage Reference	1.14	1.2	1.26	V	—

Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

3: Settling time measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

TABLE 31-18: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 4)** ECPLL **(Note 3)**
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 4)**
OS12			4	—	10	MHz	XTPLL **(Notes 3,4)**
OS13			10	—	25	MHz	HS **(Note 4)**
OS14			10	—	25	MHz	HSPLL **(Notes 3,4)**
OS15			32	32.768	100	kHz	SOSC **(Note 4)**
OS20	TOSC	TOSC = 1/FOSC = TCY **(Note 2)**	—	—	—	—	See parameter OS10 for FOSC value
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 4)**
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 4)**
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 4)**
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 4)**
OS42	GM	External Oscillator Transconductance (Primary Oscillator only)	—	12	—	mA/V	VDD = 3.3V, TA = +25°C **(Note 4)**

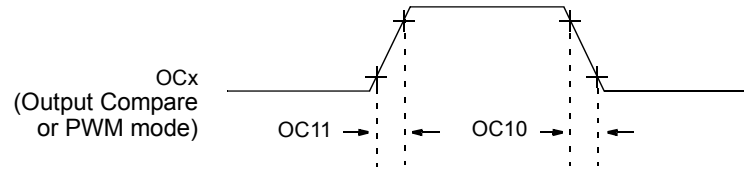
Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.

3: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

4: This parameter is characterized, but not tested in manufacturing.

FIGURE 31-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

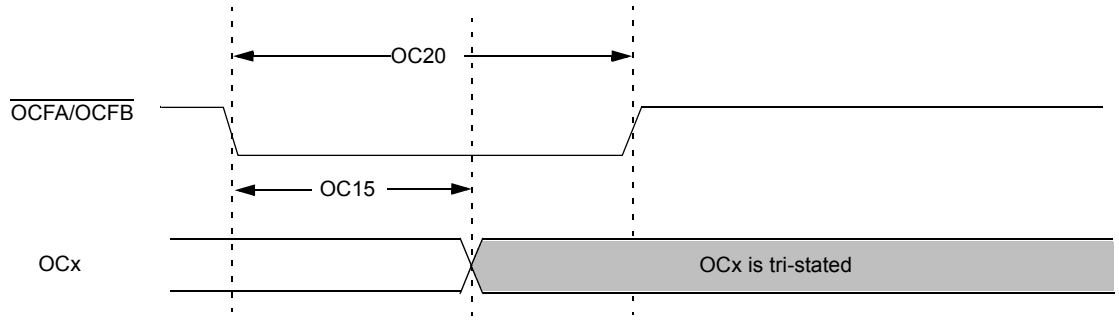
TABLE 31-27: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-9: OCx/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-28: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP52	TscH2ssH TscL2ssH	$\overline{SS}$x after SCKx Edge	Tsck + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-32: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 4)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-37: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period(2)	65	—	—	ns	See Table 31-36
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)(4)	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	2 TAD	—	—	—	—
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger(3)	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)(3)	—	0.5 TAD	—	—	—
AD63	TDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(3)	—	—	2	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

4: Refer to Table 31-36 for detailed conditions.

NOTES: